

General Purpose Transistors

NPN Silicon

MMBT2222L, MMBT2222AL, SMMBT2222AL

Features

- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable

MAXIMUM RATINGS

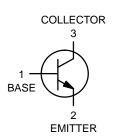
Rating	Symbol	Value	Unit
Collector – Emitter Voltage MMBT2222L MMBT2222AL, SMMBT2222AL	V _{CEO}	30 40	Vdc
Collector-Base Voltage MMBT2222L MMBT2222AL, SMMBT2222AL	V _{CBO}	60 75	Vdc
Emitter – Base Voltage MMBT2222L MMBT2222AL, SMMBT2222AL	V _{EBO}	5.0 6.0	Vdc
Collector Current – Continuous	I _C	600	mAdc
Collector Current – Peak (Note 3)	I _{CM}	1100	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate (Note 2) T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.
- 3. Reference SOA curve.





SOT-23 CASE 318 STYLE 6

MARKING DIAGRAM



xxx = 1P or M1B M = Date Code* • = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

ELECTRICAL CHARACTERISTICS ($T_A = 25$ °C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (I _C = 10 mAdc,	I _B = 0) MMBT22 MMBT222	(DIV)CLO	30 40	_ _	Vdc
Collector – Base Breakdown Voltage ($I_C = 10 \mu Adc, I_E$	V _{(BR)CBO} V _{(BR)CBO}	60 75	- -	Vdc	
Emitter-Base Breakdown Voltage (I_E = 10 μ Adc, I_C =	MMBT22 MMBT222		5.0 6.0	- -	Vdc
Collector Cutoff Current (V _{CE} = 60 Vdc, V _{EB(off)} = 3.0 Vdc)	MMBT2222A, SMMBT222	I _{CEX}	-	10	nAdc
Collector Cutoff Current ($V_{CB} = 50 \text{ Vdc}$, $I_{E} = 0$) ($V_{CB} = 60 \text{ Vdc}$, $I_{E} = 0$) ($V_{CB} = 50 \text{ Vdc}$, $I_{E} = 0$, $T_{A} = 125^{\circ}\text{C}$) ($V_{CB} = 60 \text{ Vdc}$, $I_{E} = 0$, $T_{A} = 125^{\circ}\text{C}$)	MMBT22 MMBT2222A, SMMBT222 MMBT22 MMBT2222A, SMMBT222	22A 222	- - - -	0.01 0.01 10 10	μAdc
Emitter Cutoff Current (V _{EB} = 3.0 Vdc, I _C = 0)	MMBT2222A, SMMBT222	22A I _{EBO}	-	100	nAdc
Base Cutoff Current (V _{CE} = 60 Vdc, V _{EB(off)} = 3.0 Vdc	c) MMBT2222A, SMMBT222	22A I _{BL}	-	20	nAdc
ON CHARACTERISTICS		1	•	•	•
DC Current Gain $ \begin{array}{l} (I_C=0.1 \text{ mAdc, } V_{CE}=10 \text{ Vdc}) \\ (I_C=1.0 \text{ mAdc, } V_{CE}=10 \text{ Vdc}) \\ (I_C=10 \text{ mAdc, } V_{CE}=10 \text{ Vdc}) \\ (I_C=10 \text{ mAdc, } V_{CE}=10 \text{ Vdc, } T_{A}=-55^{\circ}\text{C}) \\ (I_C=150 \text{ mAdc, } V_{CE}=10 \text{ Vdc, } (\text{Note 4}) \\ (I_C=150 \text{ mAdc, } V_{CE}=10 \text{ Vdc) } (\text{Note 4}) \\ (I_C=500 \text{ mAdc, } V_{CE}=10 \text{ Vdc) } (\text{Note 4}) \\ \end{array} $	MMBT2222A o MMBT22 MMBT2222A, SMMBT222	222	35 50 75 35 100 50 30 40	- - - 300 - -	-
Collector – Emitter Saturation Voltage (Note 4) (I _C = 150 mAdc, I _B = 15 mAdc)	MMBT22 MMBT2222A, SMMBT222		- -	0.4 0.3	Vdc
$(I_C = 500 \text{ mAdc}, I_B = 50 \text{ mAdc})$	MMBT22 MMBT2222A, SMMBT222			1.6 1.0	
Base – Emitter Saturation Voltage (Note 4) (I _C = 150 mAdc, I _B = 15 mAdc)	MMBT22 MMBT2222A, SMMBT222		_ 0.6	1.3 1.2	Vdc
$(I_C = 500 \text{ mAdc}, I_B = 50 \text{ mAdc})$	MMBT22 MMBT2222A, SMMBT222			2.6 2.0	
SMALL-SIGNAL CHARACTERISTICS			•		
Current – Gain – Bandwidth Product (Note 5) (I _C = 20 mAdc, V _{CE} = 20 Vdc, f = 100 MHz)	MMBT22 MMBT2222A, SMMBT222		250 300	_ _	MHz
Output Capacitance (V _{CB} = 10 Vdc, I _E = 0, f = 1.0 MHz)		$C_{ m obo}$	_	8.0	pF
Input Capacitance (V _{EB} = 0.5 Vdc, I _C = 0, f = 1.0 MHz)	MMBT22 MMBT2222A, SMMBT222		- -	30 25	pF
Input Impedance (I _C = 1.0 mAdc, V_{CE} = 10 Vdc, f = 1.0 kHz) (I _C = 10 mAdc, V_{CE} = 10 Vdc, f = 1.0 kHz)	MMBT2222A, SMMBT222 MMBT2222A, SMMBT222		2.0 0.25	8.0 1.25	kΩ
Voltage Feedback Ratio ($I_C = 1.0 \text{ mAdc}$, $V_{CE} = 10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$) ($I_C = 10 \text{ mAdc}$, $V_{CE} = 10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$)	MMBT2222A, SMMBT222 MMBT2222A, SMMBT222		- -	8.0 4.0	X 10 ⁻⁴
Small – Signal Current Gain ($I_C = 1.0$ mAdc, $V_{CE} = 10$ Vdc, $f = 1.0$ kHz) ($I_C = 10$ mAdc, $V_{CE} = 10$ Vdc, $f = 1.0$ kHz)	MMBT2222A, SMMBT222 MMBT2222A, SMMBT222		50 75	300 375	-

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic			Min	Max	Unit
SMALL-SIGNAL CHARACTERISTICS			•		•
Output Admittance ($I_C = 1.0 \text{ mAdc}$, $V_{CE} = 10 \text{ Vdc}$, $f = 1.0 \text{ kH}$ ($I_C = 10 \text{ mAdc}$, $V_{CE} = 10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$		h _{oe}	5.0 25	35 200	μmhos
Collector Base Time Constant (I _E = 20 mAdc, V _{CB} = 20 Vdc, f = 31.8 MHz) MMBT2222A, SMMBT2222A			-	150	ps
Noise Figure (I _C = 100 μ Adc, V _{CE} = 10 Vdc, R _S = 1.0 k Ω , f = 1.0 kHz) MMBT2222A, SMMBT2222A			-	4.0	dB
SWITCHING CHARACTERISTICS (MMBT2	222A only)		•		•
Delay Time	$(V_{CC} = 30 \text{ Vdc}, V_{BE(off)} = -0.5 \text{ Vdc},$	t _d	_	10	
Rise Time	$(V_{CC} = 30 \text{ Vdc}, V_{BE(off)} = -0.5 \text{ Vdc}, \\ I_{C} = 150 \text{ mAdc}, I_{B1} = 15 \text{ mAdc})$	t _r	_	25	ns
Storage Time	$(V_{CC} = 30 \text{ Vdc}, I_{C} = 150 \text{ mAdc},$		-	225	
Fall Time	$I_{B1} = I_{B2} = 15 \text{ mAdc}$	t _f	_	60	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 4. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.
- 5. f_T is defined as the frequency at which |h_{fe}| extrapolates to unity.

SWITCHING TIME EQUIVALENT TEST CIRCUITS

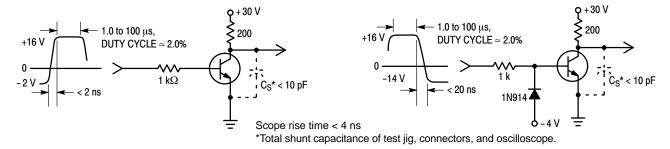


Figure 1. Turn-On Time

Figure 2. Turn-Off Time

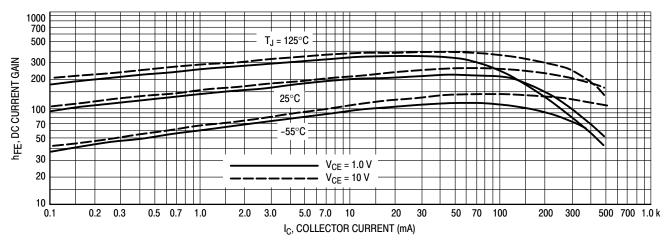


Figure 3. DC Current Gain

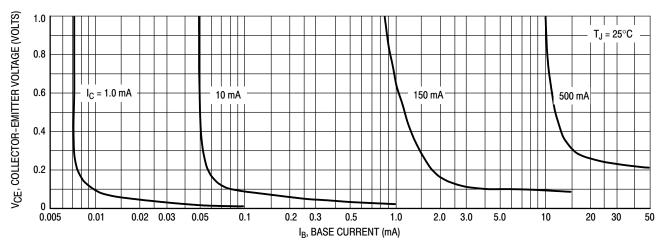


Figure 4. Collector Saturation Region

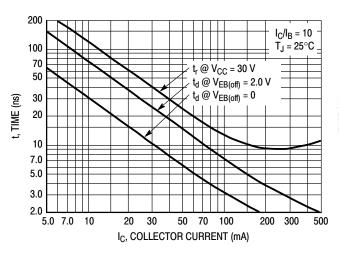


Figure 5. Turn-On Time

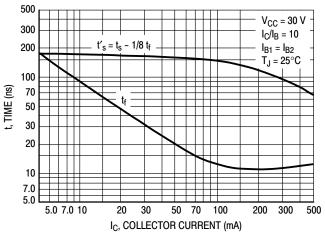


Figure 6. Turn-Off Time

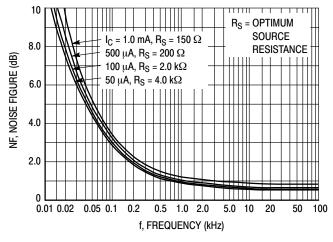


Figure 7. Frequency Effects

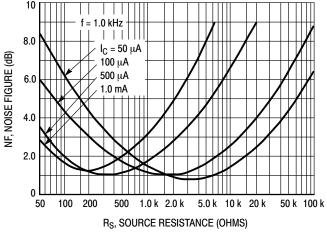
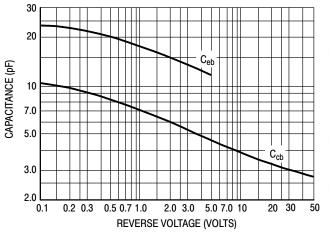


Figure 8. Source Resistance Effects

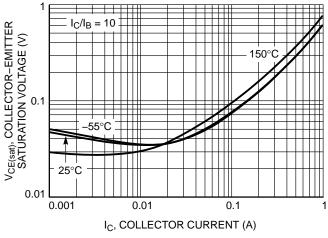
1.3



f_T, CURRENT-GAIN BANDWIDTH PRODUCT (MHz) 500 V_{CE} = 20 V $T_J = 25^{\circ}C$ 300 200 100 70 50 70 100 1.0 2.0 3.0 5.0 7.0 20 50 IC, COLLECTOR CURRENT (mA)

Figure 9. Capacitances

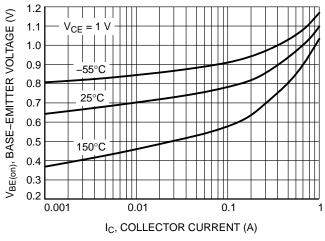
Figure 10. Current-Gain Bandwidth Product



1.2 $I_C/I_B = 10$ V_{BE(sat)}, BASE-EMITTER SATURATION VOLTAGE (V) 1.1 1.0 0.9 -55°C 0.8 25°C 0.7 0.6 150°C 0.5 0.4 0.3 0.2 0.001 0.01 0.1 I_C, COLLECTOR CURRENT (A)

Figure 11. Collector Emitter Saturation Voltage vs. Collector Current

Figure 12. Base Emitter Saturation Voltage vs.
Collector Current



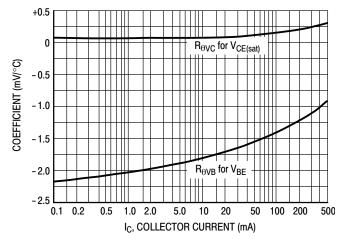


Figure 13. Base Emitter Voltage vs. Collector Current

Figure 14. Temperature Coefficients

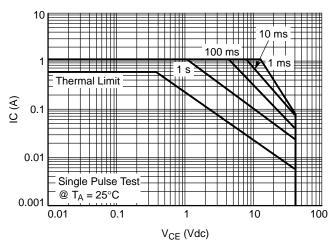


Figure 15. Safe Operating Area

ORDERING INFORMATION

Device	Specific Marking Code	Package	Shipping [†]
MMBT2222LT1G	M1B	SOT-23 (Pb-Free)	3000 / Tape & Reel
MMBT2222ALT1G, SMMBT2222ALT1G	1P	SOT-23 (Pb-Free)	3000 / Tape & Reel
MMBT2222LT3G	M1B	SOT-23 (Pb-Free)	10,000 / Tape & Reel
MMBT2222ALT3G, SMMBT2222ALT3G	1P	SOT-23 (Pb-Free)	10,000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

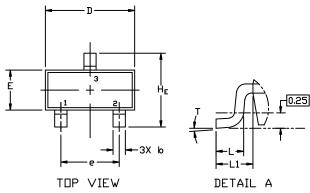




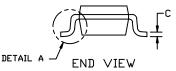
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DATE 01 MAR 2023









NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIM	ETERS			INCHES	
DIM	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
Ε	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0*		10°	0*		10°

GENERIC MARKING DIAGRAM*

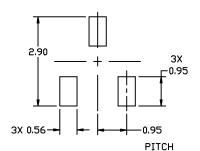


XXX = Specific Device Code

M = Date Code

■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

STYLES ON PAGE 2

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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



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DATE 01 MAR 2023

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE	1	
STYLE 9: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE	STYLE 11: PIN 1. ANODE 2. CATHODE 3. CATHODE-ANODE	STYLE 12: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 13: PIN 1. SOURCE 2. DRAIN 3. GATE	STYLE 14: PIN 1. CATHODE 2. GATE 3. ANODE
STYLE 15: PIN 1. GATE 2. CATHODE 3. ANODE	STYLE 16: PIN 1. ANODE 2. CATHODE 3. CATHODE	STYLE 17: PIN 1. NO CONNECTION 2. ANODE 3. CATHODE	STYLE 18: PIN 1. NO CONNECTION 2. CATHODE 3. ANODE	STYLE 19: I PIN 1. CATHODE 2. ANODE 3. CATHODE-ANODE	STYLE 20: PIN 1. CATHODE 2. ANODE 3. GATE
STYLE 21: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT	STYLE 23: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 24: PIN 1. GATE 2. DRAIN 3. SOURCE	STYLE 25: PIN 1. ANODE 2. CATHODE 3. GATE	STYLE 26: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE				

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